

Special Issue

Novel Magnetic Materials and Magnetism in Spintronics

Message from the Guest Editor

As the field of spintronics undergoes swift advancements, an increasing array of sophisticated magnetic materials is being unveiled, showcasing parallel growth in magnetism. This Special Issue within *Inventions*, published by MDPI, spotlights key topics such as the synthesis methodologies for magnetic materials, especially nanoscale materials, advancements in 2D magnetic materials and 2D spintronic devices, techniques for measuring and characterizing magnetic materials, applications of magnetic materials, innovations in spintronic devices, and the exploration of magnetism associated with novel magnetic materials and spintronic devices.

Guest Editor

Prof. Dr. Yanfeng Jiang

Department of Electrical Engineering, Jiangnan University, Wuxi 214122, China

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Inventions
Editorial Office
MDPI, Grosspeteranlage 5
4052 Basel, Switzerland
Tel: +41 61 683 77 34
inventions@mdpi.com

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Prof. Dr. Chien-Hung Liu

Department of Mechanical Engineering, National Chung Hsing University, 250 Kuo Kuang Rd., Taichung 402, Taiwan

Prof. Dr. Shouu-Jinn Chang

Department of Electrical Engineering, National Cheng Kung University, Tainan 701, Taiwan

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